

MC9S08DN16AMLC :Part Detail

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General Information

Part Number	MC9S08DN16AMLC
Description	S08DN 8-bit MCU, S08 core, 16KB Flash, 40MHz, QFP 32
Product Line	G9FZDZ61
PTI	MDTD
Material Type	Tested Packaged Device
Life Cycle Description (code)	REMOVED FROM ACTIVE PORTFOLIO
Status	No Longer Manufactured
Application/Qualification Tier	10-YEARS APPLICATION LIFE

Package Information

Package Type and Termination Count	QFP 32
Package Description and Mechanical Drawing	LQFP 32 7*7*1.4P0.8
Device Weight(g)	0.18860
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	7.000
Package Width (nominal)(mm)	7.000
Package Thickness (nominal)(mm)	1.600
Maximum Height Above Board(mm)	1.600
Tape & Reel	No

Environmental and Compliance Information

Pb-Free	
RoHS Compliant	
Halogen Free	Yes
Material Composition Declaration (MCD)	Download MCD Report Download MCD Report

2nd Level Interconnect	e3
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PPT)(°C)	260
Maximum Time at Peak Temperature (s)	40
Number of Reflow Cycles	3
REACH SVHC	NXP REACH Statement
UL94 (plastics flammability test)	V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed

Manufacturing Information

Micron Size(μm)	.25
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Ordering Information

Exempt from Minimum Delivery Value	Yes
Export Control Classification Number (US)	3A991A2
Harmonized Tariff (	
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US Currency	-
Device Sample Availability	03 Nov 2008
Device Production Availability	03 Nov 2008
Order	

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
15932	Product Change Notice	S08DZ60 (32ld) S08DZ128 (48ld) Copper Wire Qualification	06 Nov 2013	06 Nov 2013
15375	Product Bulletin	DZ60 2M74K ERRATA DISTRIBUTION	21 Sep 2012	22 Sep 2012
14886	Product Bulletin	S08DZ60 Input Hysteresis Tuning	03 Oct 2011	12 Oct 2011
14726	Product Change Notice	MC9S08DZ60 IMM Product Mask Revision	09 Jun 2011	07 Sep 2011
14515	Product Change Notice	0.25UM Copper Wire Qualification	26 Apr 2011	10 Sep 2011
13796	Product Bulletin	9S08 D-Family Consumer and Industrial Parts Burn-in Elimination	01 Sep 2009	02 Sep 2009

Operating Characteristics

	Low Voltage Detect POR Temperature Sensor Internal Voltage Regulator Analog Comparator
Ambient Operating Temperature (Min-Max) (°C)	-40 to 125
Bus Frequency (Max) (MHz)	20
Core Type	S08
EEPROM (KB)	0.512
GPIOs	26
Internal Flash (KB)	16
Internal RAM (KB)	1
Operating Frequency (Max) (MHz)	40
Sample Exception Availability	N
Supply Voltage (Min-Max) (V)	2.7 to 5.5
Timer Features	Input Capture Output Compare PWM Watchdog
Timer type	Real Time Clock

Reliability Data Lookup

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